# RENESAS

## ZSSC3230

Sensor Signal Conditioner IC for Capacitive Sensors

### Description

The ZSSC3230 is a CMOS integrated circuit for accurate capacitance-to-digital conversion and sensor-specific correction of capacitive sensor signals. Digital compensation of sensor offset, sensitivity. and temperature drift is accomplished via an internal digital signal processor running a correction algorithm with calibration coefficients stored in a nonvolatile, multipletime programmable (NVM) memory. Programming the ZSSC3230 is simple via the serial interface. The interface is used for the PC-controlled calibration procedure, which programs the set of calibration coefficients in memory. The ZSSC3230 is configurable for capacitive sensors with capacitances up to 30pF and will provide an output resolution that is scalable up to 18-bit. It is compatible with single-ended capacitive sensors. Measured and corrected sensor values can be output as I2C ( $\leq$  3.4MHz).

The ZSSC3230 provides accelerated signal processing, increased resolution, and improved noise immunity in order to support high-speed control, safety, and real-time sensing applications with the highest requirements for energy efficiency.

### **Typical Applications**

- Humidity sensors
- Pressure sensors, level sensors
- Smart, digital, capacitive sensors for energy-efficient solutions
- Consumer / white goods (e.g., HVAC)
- Medical applications

### **Physical Characteristics**

- Supply voltage VDD: 1.68V to 3.6V
- Operating temperature: -40°C to 125°C depending on the part code
- I2C Interface compatible, supporting
  - Standard Mode(100kHz)
  - Fast Mode (400kHz)
  - High-Speed Mode (3.4MHz)
  - Capacitive input range 0 to 30pF
- Capacitive offset compensation 0 to 15pF
- Available in 4 × 4 mm<sup>2</sup> 24-PQFN package or as die

#### **Features**

- Low current consumption: 1.3µA at 1 sample per second
- Maximum target input capacitance: 30pF
- Programmable capacitance span and offset
- High sampling rate with 2ms at 14-bit resolution
- ADC resolution: Adjustable in speed and resolution, 18-bit maximum
- Internal auto-compensated temperature sensor; not stress sensitive
- Programmable measurement sequence, single-shot and automatic cycling of measurements with end-ofsequence interrupt output
- Oversampling modes using internal averaging
- Interrupt features
- Integrated NVM for configuration and free space for customer use
- Small die size
- External reset pin (low active)
- No external trimming components required
- Highly integrated CMOS design



Figure 1. Basic Application Diagram

### **Block Diagram**



## **Typical Application Examples**



Figure 2. Isolated C Mode





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## 1. Pin Assignments

The ZSSC3230 is available as 8-inch wafer\* and QFN24 package. Details about the package are provided in section 7.



Figure 4. Pin Assignments for 4 × 4 mm 24-PQFN Package – Top View



Figure 5. Pin (Pad) Assignments for Bare-Die



<sup>\*</sup> Detailed information about wafer-shipments, etc., is available on request. See last page for contact information.

## 2. Pin Descriptions

Pin Number	Name	Туре	Description
1	n.c.	_	No connection. Leave pin floating.
2	C0	Analog Input	Capacitor input signal.
3	CC'	Analog Input	Capacitor input signal, duplicate of CC (pin 17).
4	RESQ	Digital Input	RESET, low active; internal pull-up.
5	Renesas-Test	_	Connect to VSS; otherwise no connection; leave pin floating.
6	n.c.	_	No connection. Leave pin floating.
7	n.c.	_	No connection. Leave pin floating.
8	SCL	Digital Input	Clock input for I2C interface.
9	n.c.	_	No connection. Leave pin floating.
10	n.c.	-	No connection. Leave pin floating.
11	SDA	Digital Input/Output	Bi-directional data I/O for I2C. Pull-up to VDD.
12	n.c.	_	No connection. Leave pin floating.
13	n.c.	_	No connection. Leave pin floating.
14	Renesas-Test	-	Connect to VSS; otherwise no connection; leave pin floating.
15	EOC	Digital Output	End-of-conversion and output interrupt signal.
16	PDM	Digital Output	Digital output for pulse-density modulated output.
17	CC	Analog Input	Capacitor input signal, duplicate to CC' (pin 3).
18	n.c.	-	No connection. Leave pin floating.
19	n.c.	-	No connection. Leave pin floating.
20	VSS	Ground	Power supply ground.
21	n.c.	_	No connection. Leave pin floating.
22	n.c.	_	No connection. Leave pin floating.
23	VDD	Supply	Power supply.
24	n.c.	_	No connection. Leave pin floating.

#### Table 1. Pin Descriptions

## 3. Absolute Maximum Ratings

The absolute maximum ratings are stress ratings only. Stresses greater than those listed below can cause permanent damage to the device. Functional operation of the ZSSC3230 at absolute maximum ratings is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

Symbol	Parameter	Conditions	Minimum	Maximum	Units
TJ	Junction temperature		-	135	°C
Ts	Storage temperature		-45	150	°C
	ESD – Human Body Model		-	2000	V
	ESD – Charged Device Model		-	750	V
	Latch-up		-100	+100	mA
VDD <sub>max</sub>	Voltage supply range	Referenced to VSS	-0.3	3.63	V
V <sub>IF_max</sub>	Voltage at digital interface pins	I2C pins: SDA, SCL	-0.3	VDD +0.5V or 3.63V max.	V

#### Table 2. Absolute Maximum Ratings

## 4. Recommended Operating Conditions

#### Table 3. Recommended Operating Conditions

Symbol	Parameter	Minimum	Typical	Maximum	Units
V <sub>DD</sub>	Power supply voltage	1.68	-	3.6	V
T <sub>A</sub>	Ambient temperature	-40	-	125	°C
C <sub>VDD</sub>	External (parasitic) capacitance between VDD and VSS	0	10	-	nF
SR <sub>VDD_POR</sub>	Recommended V <sub>DD</sub> rise slew rate for power-on-reset (POR) <sup>[a]</sup>	10	_	-	V/ms

[a] Per design, there is no (theoretical) minimum V<sub>DD</sub> slew-rate to trigger a clean POR; however, a reasonable slew rate is recommended.

## 5. Electrical Characteristics

All parameter values are valid only under specified operating conditions. All voltages are referenced to Vss.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
IC Supply	1	1	ı		1	
l <sub>IC</sub>	Current consumption, active ZSSC3230	Excluding connected sensor elements; noise_mode = 0; see Table 16	-	750	1100	μA
I <sub>IDLE</sub>	Idle current consumption, ZSSC3230 in Sleep State		-	0.07	1	μA
I <sub>AVE</sub>	Average current draw	Mean current consumption for one complete SSC-measurement cycle per second at 14-bit digital-only output, <i>noise_mode</i> = 0	-	1.7	3.3	μA
PSRR	Static power supply rejection ratio (PSRR)	VDD = 3V	-	40	-	dB
CDC Charac	teristics					
CRANGE	Sensor capacitance range		0	_	30	pF
C <sub>OFFSET</sub>	Absolute sensor capacitance offset		0	-	15	pF
$C_{\text{SIGNAL}}$	Effective sensor capacitance		-15	-	15	pF
f <sub>clk</sub>	Analog base clock frequency		-	750	-	kHz
ENOB	Effective number of bits, $\pm 3\sigma_{Noise}$	r <sub>ADC</sub> = 18-bit, no oversampling	-	14.4	-	Bit
Analog-to-D	vigital Converter (ADC, A2D	)	1		1	
r <sub>ADC</sub>	Resolution		12	-	18	Bit
f <sub>S,RAW</sub>	Conversion rate; conversions per second	Single external sensor A2D conversion (including auto-zero measurement AZ); resolution and mode dependent	94	-	1250	Hz
f <sub>s,corr</sub>	SSC-conversion rate for full SSC cycle; conversions per second	Full SSC-measurements per second: temperature (14-bit) + capacitance (12 to18 bit)	86	-	555	Hz
f <sub>S,TEMP</sub>	SSC-conversion rate for temperature measurement	14-bit resolution	-	960	-	Hz
ADCnoise	ADC-noise sigma	r <sub>ADC</sub> = 16-bit	-	1	-	LSB
ENOB	Effective number of bits, $\pm 3\sigma_{\text{Noise}}$	r <sub>ADC</sub> = 18-bit, no oversampling	-	16	-	Bit
Power-Up C	onditions	•				
t <sub>stup1</sub>	Start-up time communication	Delay between VDD ramp up and start of first command (proven by design)	-	_	1	ms
t <sub>stup2</sub>	Start-up time analog operation	Delay between VDD ramp up and analog operation (proven by design)	-	-	2.5	ms

#### **Table 4. Electrical Characteristics**

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
t <sub>wup1</sub>	Wake-up time communication	Delay between sleep state and start of first command (proven by design)	-	_	0.5	ms
t <sub>wup2</sub>	Wake-up time analog operation	Delay between sleep state and analog operation (proven by design)	-	-	2	ms
Sensor Sigr	al Conditioning Performan	ce				
f <sub>SSCout</sub>	Output (update) rate	SSC-corrected digital output rate; capacitance sensor measurement: 16-bit; temperature measurement: 14-bit; noise_mode = 0; see Table 16	_	290	_	Hz
Err <sub>A,IC</sub>	ZSSC3230 accuracy error using internal SSC calculation math	Accuracy error for sensor being ideally linear (for temperature and measurand)	_	0.1	_	%FSO
Oscillator						
f <sub>CLK</sub>	Internal oscillator frequency		-	3.0	_	MHz
Temperatur	e Sensor(s)					
r <sub>Temp</sub>	Internal temperature sensor resolution		-	55	-	LSB/K
Interface an	d Memory					
f <sub>C,I2C</sub>	I2C clock frequency		_	_	3.4	MHz
t <sub>PROG</sub>	NVM program time	Programming time per 16-bit word	-	20	-	ms
n <sub>NVM</sub>	NVM endurance	Number of reprogramming cycles	1000	10000	-	Numeric
t <sub>RET,NVM</sub>	Data retention		10	_	_	Years



## 6. Device Description

The ZSSC3230 can be set up for one of three main operating modes:

- Sleep Mode Sleep Mode based operation is recommended for smart sensors for the lowest average power consumption. The ZSSC3230 automatically enters an idle state after command execution for minimum current consumption; however, the interface is still listening and accepts commands. After receiving of a valid command, the ZSSC3230 wakes up, executes the command, and provides the results at the digital interface and then returns to Sleep State.
- Command Mode Command Mode is most appropriate for evaluation, test, and calibration purposes. In this mode, all
  commands are available, both digital and analog outputs are supported, and no restrictions for any functionality need
  to be considered. Command Mode can be used for applications requiring re-occurring (or even continuous) digital
  interaction and minimum latency. Applications in Command Mode are only active on command request. See Table 15
  for definitions of the commands.
- Cyclic Measurement Mode Cyclic operation means autonomous, cyclically repeated sensor measurements and related digital and output updates.

After power-on, the voltage regulators are switched on, and the ZSSC3230's low-voltage section (LV) is active while the related interface configuration information is read from memory. Then the LV section is switched off, the ZSSC3230 goes into Sleep Mode, and the interface is ready to receive commands. The interface is always powered by  $V_{DD}$ , so it is referred to as the high voltage section (HV).

Figure 6 shows the ZSSC3230 main operation modes: Normal Mode (which uses two operation principles: "Sleep" and "Cyclic") and Command Mode. The Normal Mode automatically returns to Sleep Mode after executing the requested measurements, or periodically wakes up and conducts another measurement according to the setting for the sleep duration configured by the *CYC\_period* (bits[14:12] in memory register  $02_{HEX}$ ; see Table 16). In Command Mode, the ZSSC3230 remains active if a dedicated command (e.g., Start\_NOM) is sent, which is helpful during calibration. Command Mode can only be entered if a Start\_CM (command A9\_{HEX}; see Table 15) is the first command received after a POR.



Figure 6. Main Operating Modes of the ZSSC3230



#### 6.1 Signal Flow

See Figure 2 and Figure 3 for the ZSSC3230 block diagram sensors input options. The CC pin is duplicated as CC' depending on the preferred physical sensor connection. Selecting CC or CC' can be done using the signal setup  $CC_{pin}$  selection bits[1:0] in memory register 19<sub>HEX</sub> (see Table 16).

Two sensor connections are possible:

- Differential Measurement Mode, which is an isolated C mode with C<sub>MEAS</sub> connected between CC and C0 or CC' and C0 so that both ends of the capacitor are connected to the ZSSC3230.
- Single-Ended Measurement Mode, which is a grounded C mode with C<sub>MEAS</sub> connected between CC and VSS or CC' and VSS/ground. In this mode, C0 is switched to VSS. In this mode, only one capacitor input pin needs to be directly connected to the ZSSC3230.

The capacitance amplifier (CapAmp), which is also referred to as the charge-voltage converter (CVC), measures an external capacitance value, C<sub>MEAS</sub> and provides a differential output voltage proportional to the capacitance (change) to the subsequent ADC. Thereby C<sub>MEAS</sub> is connected with both ends to the IC or with one pin to VSS.

The bias current for the stage (CapAmp) can be programmed (using the setup signal *noise\_mode* bit 8 in the *Sensor\_config* memory register 12<sub>HEX</sub>; see Table 16) to allow a trade-off between current consumption and achievable signal to noise ratio (SNR).

The system control unit controls the analog circuitry to perform the measurement types for the external capacitive sensor and internal temperature. The multiplexer selects the signal input to the amplifier, which can be the voltage-converted signals of the external capacitive sensor or the internal temperature reference sensor signal. A full measurement request will trigger an automatic sequence of all measurement types and all input signals.

The gain amplifier (PGA) adjusts the respective signal from the capacitance-to-voltage converter or internal temperature sensor. The ZSSC3230 employs a programmable analog-to-digital converter (ADC) optimized for conversion speed and noise suppression. The programmable resolution from 12 to 18 bits provides flexibility for adapting the conversion characteristics.

The math core accomplishes the auto-zero, span, and 1<sup>st</sup> and 2<sup>nd</sup> order temperature compensation of the measured external sensor signal. The correction coefficients are stored in the nonvolatile memory. The ZSSC3230 supports I2C interface communication for controlling the ZSSC3230, configuration, and measurement result output. An adequate PDM signal for the compensated sensor signal can be provided in Cyclic Measurement Mode at the PDM pin.

Table 5 lists the conversion time of a full corrected and compensated measurement. The temperature measurement always has a 14-bit resolution. The conversion time for the sensor channels includes a full ADC conversion plus auto-zero measurement and the corresponding CVC conversion time for this channel and the respective temperature measurement and math calculation. The 2 noise modes (bit[8] in memory register  $12_{HEX}$ ) are listed separately.

adc_bits[7:6]		ADC Resolution	Conversion Time for Full Temperature Compensated Measurement, Typi $[\mu s]$		
bit[7]	bit[6]	[Bits]	noise_mode = 0	noise_mode = 1	
0	0	12	1770	2550	
0	1	14	2310	3850	
1	0	16	3390	6440	
1	1	18	5520	11630	

#### Table 5. Conversion Time for Full Temperature Compensated Measurement



### 6.2 Capacitive Sensor Front-End

The capacitance amplifier input range ( $C_{RANGE}$ ) must be adjusted to the external capacitance conditions for signal ( $C_{SIGNAL}$ ) and offset shift ( $C_{OFFSET}$ ) as given in Equation 1. See Figure 7 for an illustration of the terms.

$$C_{RANGE} = C_{OFFSET} + C_{SIGNAL}$$

#### Equation 1

 $C_{OFFSET}$  operates as a zero-shift capacitance to cancel a given offset by the sensor. The offset-shift capacitance must not exceed the selected input capacitance range  $C_{RANGE}$ . For  $C_{OFFSET}$ , the respective configuration must be set up in the EEPROM for the *shift\_cap* parameter (bits[5:0] in memory register 12<sub>HEX</sub>; see Table 16).

The correlating setup for  $C_{SIGNAL}$  must be done in the EEPROM for parameter *cap\_range* (bits[13:9] in memory register 12<sub>HEX</sub>). In Table 16, the respective values are given. These values can be measured in the positive and negative direction, so the effective range of  $C_{SIGNAL}$  will be doubled compared to the *cap\_range* setting. The principle is shown in Figure 7.



Figure 7. Capacitive Input Signal Conditions



### 6.2.1 Differential Mode

The most relevant measurement mode is the Differential Measurement Mode, with  $C_{MEAS}$  connected between CC and C0 or CC' and C0 so that both ends of the capacitor are connected to the ZSSC3230. For electrical connections, see Figure 8.

For the ZSSC3230 for the Differential Measurement Mode, the configuration must be done in the EEPROM for parameter *sensecap\_type* (bit[15] in memory register  $12_{HEX}$ ; see Table 16). When the *sensecap\_type* is 0, the differential mode is selected, which is the default configuration.



Figure 8. Capacitive Input in Differential Mode

#### 6.2.2 Single-Ended Mode

Another measurement mode is the single ended measurement mode, with CMEAS connected between CC and VSS or CC' and VSS/ground. In this mode C0 is switched to VSS. In this mode only 1 Pin needs to be directly connected to the IC.

Configuring the ZSSC3230 for Single-Ended Input Mode must be done in the EEPROM via the parameter *sensecap\_type* (bit[15] in memory register 12<sub>HEX</sub>; see Table 16). Since the respective bit is defined as "0" in the default configuration for Differential Mode, the bit must be programmed to "1."

#### 6.2.3 Sensor Leakage Compensation

Sensor leakage compensation is an additional option for Single-Ended Mode to enable the sensor element's leakage current compensation. The leakage current is caused by the sensor element's parasitic resistance. Enabling this function via the *sensor\_leakage* bit[14] in memory register  $12_{\text{HEX}}$  leads to loss of dynamic range and a decrease in the SNR. With losing 1-bit effective resolution on leakage compensation, the respective capacitive input range for C<sub>SIGNAL</sub> will be doubled compared to the description in section 6.2.





Figure 9. Capacitive Input in Single-Ended Mode

### 6.2.4 Shield Driver Mode

The Shield Driver Mode is a special sub-mode for Single-Ended Mode. In this mode, the C0 pin will be forced to the same level as the CC/CC' pin. This pin can be used to drive a shield, so the shield parasitic capacitance does not have an effect on the measurement. The Shield Driver Mode can be enabled by setting the EEPROM parameter *En\_shlddrv* (bit[4] in memory register  $19_{HEX}$ ) to "1" (see Table 16).



Figure 10. Shield Driver Mode

#### 6.2.5 Subtraction Mode

The Subtraction Mode is a special sub-mode for Single-Ended Mode. It is activated by setting the  $En_sh2$  bit to "1" (bit[3] in memory register 19<sub>HEX</sub>; see Table 16). In this mode, C0 is charged to the opposite reference of the CC/CC' node level. In conversion phase the charge of CC/CC' and C0 are integrated. In this mode, the integrated capacitance corresponds to "Cx-Cy"; thus this mode can provide an additional range extension.



Figure 11. Subtraction Mode

#### 6.3 Temperature Sensor

The ZSSC3230 provides a PTAT-based internal temperature sensor measurement to allow compensation for temperature effects. The temperature output signal is a differential voltage that is adapted by the amplifier (PGA) for the ADC input. For IC-internal temperature measurements, the respective settings are defined and programmed in the NVM by Renesas. The resolution setting for temperature measurements is defined as 14-bit.

### 6.4 Analog to Digital Converter (ADC)

An analog-to-digital converter (ADC) is used to digitize the amplifier signal. To allow optimizing the trade-off between conversion time and resolution, the resolution can be programmed from 12-bit to 18-bit by configuring the parameter  $adc_bits$ , (bits [7:6] in memory register  $12_{HEX}$ ; see Table 16). The ADC processes differential input signals provided by the internal amplifier for sensor measurement and temperature measurement. The application default setting is 16-bit. The corresponding conversion times are listed in Table 6. The conversion time for the sensor channels includes a full ADC conversion as well as the corresponding CVC conversion time for this channel. There are 2 noise modes (selected with bit[8] in memory register  $12_{HEX}$ ). The listed conversion times are valid for raw measurements including auto-zero compensation.

adc_bits[7:6]				(including CVC), typical Is]	Conversion Time
bit[7]	bit[6]	ADC Resolution [Bits]	noise_mode = 0	noise_mode = 1	Temperature, Typical [µs]
0	0	12	770	1550	630
0	1	14	1310	2850	1040
1	0	16	2390	5440	1810
1	1	18	4550	10620	3470

Table 6. ADC Resolution and Conversion Times for a Single Analog-to-Digital Conversion with Auto-Zero



#### 6.5 Calibration Math

The data path internally calculates with a 26-bit two's-complement integer representation. The coefficients in the memory are stored as integers in sign-magnitude representation (1-bit sign + 23-bit magnitude). Each multiplication scales the product by 2<sup>23</sup>. There is an option to preprocess the data by applying a 1/C algorithm. 1/C is typically used to pre-process transfer characteristics for capacitive pressure sensors. A principle flow is shown in Figure 12.

Internal overflows and underflows are detected and the result is automatically saturated. The saturation is reported in the status byte.



Figure 12. Principal Compensation Flow

### 6.5.1 (2-1/C) Pre-compensation

For capacitive pressure sensors, a pre-compensation of the ADC signal might be beneficial. Using this function will help to fit the typical pressure sensor transfer characteristic to matching the second-order compensation input requirements for more accurate compensation results. If the (2-1/C) pre-compensation is activated, it will apply only in Normal Measurement Mode with math compensation, not in RAW measurements using Command Mode. The respective (2-1/C) calculation for determination of calibration coefficients is handled in the respective *calibration.dll*. This feature can be enabled by setting the corresponding bit *siginv* (bit[11] in memory register  $02_{HEX}$ ; see Table 16). Before the 1/C math is applied, the ADC value of the respective sensor input signal will be inverted.

This leads to the following transfer function for *S\_raw* with the system transfer function that is shown in Figure 13.

$$S_{rawi} = \left[2^{24} - \frac{2^{46}}{S_{raw}}\right]_{-2^{25}}^{2^{25}-1}$$
Equation

Note: For the application, if a "Crange/CSers" inversion will be performed, the shift capacitor must to be set to "0."

2



Figure 13. System Transfer Function for 2-1/C

#### 6.5.2 Sensor Signal Compensation Math

The  $SOT\_curve$  (bit [15] in EEPROM word  $02_{HEX}$ ; see Table 16) selects whether second-order equations compensate for sensor nonlinearity with a parabolic or S-shaped curve. The parabolic compensation is recommended.

Equations for the Parabolic *SOT\_curve* Setting (*SOT\_curve* = 0):

The coefficients from the memory (23-bit absolute and 1-bit sign; see Table 7) are read into 26-bit-wide registers in the calculation block. The 24-bit-memory coefficients are shifted by two bits so that the MSB of the 24-bit memory coefficient is placed at the MSB of the 26-bit calculation register coefficient.

Simplified:

$$K_{1} = 2^{23} + \frac{T\_Raw}{2^{23}} \cdot \left(\frac{4 \cdot SOT\_tcg}{2^{23}} \cdot T\__{Raw} + 4 \cdot Tcg\right)$$
Equation 3
$$K_{2} = 4 \cdot Offset\_S + S\_Raw + \frac{T\_Raw}{2^{23}} \cdot \left(\frac{4 \cdot SOT\_tco}{2^{23}} \cdot T\__{Raw} + 4 \cdot Tco\right)$$
Equation 4
$$Z_{SP} = \frac{4 \cdot Gain\_S}{2^{23}} \cdot \frac{K_{1}}{2^{23}} \cdot K_{2} + 2^{23}$$
(Bounded to positive number range)
Equation 5
$$S = \frac{Z_{SP}}{2^{23}} \cdot \left(\frac{4 \cdot SOT\_sensor}{2^{23}} \cdot Z_{SP} + 2^{23}\right) + Sensor\_Shift$$
(Bounded to positive number range)
Equation 6



Equations for the S-shaped SOT\_curve Setting (SOT\_curve = 1):

Simplified:

$$Z_{SS} = \frac{4 \cdot Gain\_S}{2^{23}} \cdot \frac{K_1}{2^{23}} \cdot K_2$$
Equation 7
$$S = \frac{Z_{SS}}{2^{23}} \cdot \left(\frac{4 \cdot SOT\_sensor}{2^{23}} \cdot |Z_{SS}| + 2^{23}\right) + 2^{23} + Sensor\_Shift$$
(Bounded to positive number range)
Equation 8

Complete:

$$Z_{SS} = \left[\frac{Gain\_S}{2^{21}} \cdot \left[\frac{\kappa_1}{2^{23}} \cdot \kappa_2\right]_{-2^{25}}^{2^{25}-1}\right]_{-2^{25}}^{2^{25}-1}$$
Equation 9



Where the following representations are valid:

S	Corrected capacitive sensor reading output via I2C; range: [0 to FFFFFFHEX]
S_Raw	Raw capacitive sensor reading from ADC (after auto-zero correction); shifted range to: [-7FFFFHEX to 7FFFFHEX]
Gain_S	Capacitive sensor gain term; range: [-7FFFFHEX to 7FFFFFHEX]
Offset_S	Capacitive sensor offset term; range: [-7FFFFHEX to 7FFFFHEX]
Tcg	Temperature coefficient gain term; range: [-7FFFFHEX to 7FFFFHEX]
Тсо	Temperature coefficient offset term; range: [-7FFFFHEX to 7FFFFHEX]
T_Raw	Raw temperature reading (after AZ correction); shifted range to: [-7FFFFFHEX to 7FFFFHEX]
SOT_tcg	Second-order term for Tcg non-linearity; range: [-7FFFFFHEX to 7FFFFFHEX]
SOT_tco	Second-order term for Tco non-linearity; range: [-7FFFFFHEX to 7FFFFFHEX]
SOT_sensor	Second-order term for sensor non-linearity; range: [-7FFFFFHEX to 7FFFFFHEX]
Sensor_shift	Post-calibration, post-assembly offset shift; range: [-7FFFFFHEX to 7FFFFFHEX]
	Absolute value
$\begin{bmatrix} \dots \end{bmatrix}_{ll}^{\mu l}$	Bound number range from ll to ul; if needed, apply saturation at the limits ll or ul and report overflow/underflow in the status byte

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### 6.5.3 Temperature Signal Compensation

Temperature is measured internally. Temperature correction contains both linear gain and offset terms as well as a second-order term to correct for any nonlinearities. For temperature, second-order compensation for nonlinearity is always parabolic:

Simplified:

$$Z_T = \frac{4 \cdot Gain_T}{2^{23}} \cdot (T_Raw + 4 \cdot Offset_T) + 2^{23}$$
 (Bounded to positive number range) Equation 11

$$T = \frac{Z_T}{2^{23}} \cdot \left(\frac{4 \cdot SOT_T}{2^{23}} \cdot Z_T + 2^{23}\right) + T_Shift \text{ (Bounded to positive number range)}$$
Equation 12

Where

Т	Corrected Temperature reading output via I2C; range [0HEX to 0xFFFFFFHEX]
Gain_T	Gain coefficient for temperature; range [-7FFFFHEX to 7FFFFHEX]
T_Raw	Raw temperature reading after AZ correction; shifted range to [-7FFFFF <sub>HEX</sub> to 7FFFF <sub>HEX</sub> ]
Offset_T	Offset coefficient for temperature; range [-7FFFFHEX to 7FFFFHEX]
SOT_T	Second-order term for temperature source non-linearity; range [-7FFFF $_{HEX}$ to 7FFFF $_{HEX}$ ]
T_Shift	Shift for post-calibration/post-assembly offset compensation [-7FFFFFHEX to 7FFFFHEX]

Table 7. Data Format of Calibration Coefficients in Memory

Bit Number:	23	22	21	20	 2	1	0
Meaning, Weighting:	0 = Positive 1 = Negative	2 <sup>1</sup>	20	2 <sup>-1</sup>	 2 <sup>-19</sup>	2 <sup>-20</sup>	2 <sup>-21</sup>

### 6.6 Output Stages

The ZSSC3230 supports signal output via a PDM output pin and I2C output. Measured values are provided at an I2C output interface and at a pulse-density modulation (PDM) output. The digital interface can be used for configuration and the calibration procedure using the user's computer in order to program a set of calibration coefficients into the on-chip memory.

### 6.6.1 PDM Output Stage

To use the ZSSC3230 in PDM Output Mode, the Cyclic Measurement Mode is required. The ZSSC3230 will not go into Sleep Mode or power-down between measurements. The PDM Output Mode can be enabled via the *PDM\_enable* bit (bit[9] in memory register 02<sub>HEX</sub>; see Table 16). In this case, the PDM output will be started after power-on reset.

Note: If the ZSSC3230 is not used in PDM Output Mode, the PDM pin should not be connected.

The ZSSC3230 provides a pseudo-analog output of a sigma-delta modulator, i.e. a pulse-density stream, which can be converted into an analog DAC-like output by external low-pass filtering. The PDM signal will be output selectively at the PDM pin. The PDM output is available for the compensated sensor signal. The PDM output is scaled to a 16-bit wide output signal.

When the PDM output is used, an external capacitor must be connected to the PDM output as shown in Figure 14.



Filter Capacitance (nF)	Vout Ripple (µV/V)	0 to 90%Settling Time (ms)	Analog Output Resolution (Bit)	
100	1000.0	2.3	10	
400	250	9.2	12	
1600	62	36.8	14	
6400	16	147.2	16	

Table 8. Analog Output Performance by External Capacitor Value



Figure 14. PDM Output Configuration

#### 6.6.2 I2C Output

The ZSSC3230 supports an I2C slave interface for digital output operation. The implementation of the interfaces is such that the available commands (see section 6.7.2) and request codes for the ZSSC3230 are the same regardless on the interface type used.

Initially after power-up or reset, the I2C slave address is loaded from the on-chip NVM from the *Slave\_Addr* bits [6:0] in register 02<sub>HEX</sub>; see Table 16). There is a general status byte, which is part of the ZSSC3230's digital response on READ requests. Every response starts with a status byte followed by the data word. The data word depends on the previous command. It is possible to read the same data more than once if the read request is repeated. The next command invalidates any previous data.

Table	9.	General	Status	Byte
-------	----	---------	--------	------

Bit-Number:	7	6	5	4	3	2	1	0
Meaning:	0	Powered?	Busy?	Мс	ode	Memory Error?	ADC Overflow	Math Saturation

- Bit 7 is intentionally not assigned in order to allow for a 1 bit-length time.
- Bit 6 indicates power: 1 if device is powered, 0 if not powered.
- Bit 5 indicates whether the ZSSC3230 is busy. The data for the last command is not available yet. No new commands are processed if the device is busy. It is "1" if the device is busy.
- Bit 3 and 4 indicate the actual mode of the ZSSC3230: 00 = Normal Operation Mode; 01 = Command Mode; 10 = Test Mode. See Table 10.

- Bit 2 shows whether there has been a memory integrity/error as indicated by whether the checksum-based integrity check passed or failed: 0 if the integrity test passed; 1 if the test failed.
- Bit 1 shows whether there has been an ADC overflow, which is detected if the raw ADC-output value for capacitive measurement exceeded the nominal, digital ADC-output range, depending on the selected ADC resolution. This check is only for the raw results for the capacitive measurement.
- Bit 0 shows the status Information regarding ALU saturation. If the last executed command was a measurement
  request, this bit is 0 if any intermediate value and the final SSC result are in a valid range and no SSC-calculation
  internal saturation occurred. If the last command was a measurement request, this bit is 1 if an SSC-calculation
  internal saturation occurred. This bit is also 0 for any non-measurement command.

#### Table 10. Mode Status

Status[4:3]	Mode
00	Normal Operation Mode (sleep and cyclic operations)
01	Command Mode
10	Renesas Reserved for Test Mode
11	Renesas Reserved

The I2C interface is compliant with the *NXP I2C Bus Specification, Rev. 06* (UM10204, 4 April 2014). All modes up to High Speed Mode are supported. Slave address codes 04<sub>HEX</sub> to 07<sub>HEX</sub> must not be programmed to the ZSSC3230 since they are exclusively used for the High Speed Mode. The ZS SC3230 will support 7 bit addressing only.

In I2C Mode, each command is started as shown in Figure 15. Only the number of bytes that are needed for the command must be sent. An exception is the I2C High Speed Mode where 3 bytes must always be sent. After the execution of a command (busy = 0), the expected data can be read as illustrated in Figure 16 or if no data are returned by the command, the next command can be sent. The status can be read at any time as described in Figure 17.





#### Read Data (I2C Read)

(a) Example: after the completion of a Memory Read command



(b) Example: after the completion of a *Measure* command (AA<sub>HEX</sub>)





#### Read Status (I2C Read)





#### Table 11. I2C Interface Parameters

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
f <sub>SCL</sub>	Interface clock		0.1	-	3.4	MHz
D <sub>SPI</sub>	Duty cycle		33	-	50	%
V <sub>high,I2C</sub>	Input HIGH level voltage	Referenced to the external supply	0.7	-	1.0	V <sub>DD</sub>
V <sub>low,I2C</sub>	Input LOW level voltage	voltage V <sub>DD</sub>	0.0	-	0.3	V <sub>DD</sub>
C <sub>SDA</sub>	Capacitive load at input pin, SDA	<ul> <li>100pF ⇔ maximum for Standard and Fast Mode; in High-Speed Mode f<sub>SCL,max</sub> = 3.4MHz</li> </ul>	-	100	400	pF
		<ul> <li>400pF ⇔ only in High-Speed Mode, f<sub>SCL,max</sub> = 1.7MHz</li> </ul>				
I <sub>OL</sub>	LOW level output current	V <sub>SDA</sub> =0.4V, Standard and Fast Mode with 400kHz; 400pF load	3	6	40	mA

Details for timing and protocol of the ZSSC3230-supported I2C communication in Standard Mode, Fast Mode, and High-Speed Mode are given in the *I2C-Bus Specification*, *Rev.6*, *UM10204*.

### 6.6.3 EOC and Output Interrupt Signaling

The EOC pin can be programmed to operate either as a "measurement busy" indicator and end-of-conversion (EOC) transducer, or as a configurable interrupt transducer. The respective basic operation must be programmed into *INT\_setup* bits in the memory (bits[8:7] in NVM register  $02_{HEX}$ ; see Table 16). One or two 24-bit-quantized thresholds can be programmed (see the *Interrupt Level Setup* memory registers:  $13_{HEX}$ ,  $14_{HEX}$  and  $15_{HEX}$ ). Depending on the *INT\_setup* selection, the EOC pin provides a logic 1 or logic 0 according to the SSC-corrected measurement result. The respective thresholds are programmed left-aligned in the memory, such that they must be programmed with the threshold's MSB in the memory register's MSB, etc. The LSBs of the 24-bit threshold in the memory must be ignored according to the number of bits of the selected ADC resolution (according to *adc\_bits*).

If only the effective end-of-conversion is signaled (INT\_setup =  $00_{BIN}$ ), the EOC signal is pulled LOW for the duration of the configured conversion time. After the conversion is complete, the EOC signal is released and returns to HIGH.

The interrupt functionality is only available for digital values from the SSC-calculation unit. The interrupt feature cannot monitor any type of raw values. The encoding and data format of the interrupt thresholds is the same as for SSC-corrected measurement results (see Table 12).

Bit-Number:	23	22	21	20	 2	1	0
Meaning, Weighting:	2 <sup>0</sup>	2 <sup>-1</sup>	2-2	2 <sup>-3</sup>	 2 <sup>-21</sup>	2-22	2 <sup>-23</sup>

#### Table 12. Data Format of Interrupt Thresholds (TRSH1 and TRSH2)







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### 6.7 Measurement and Output Options

Sensor measurement results of the ZSSC3230 are provided in digital at the I2C interface. This will be the main active interaction path, and it can combined with the PDM output configuration.

#### 6.7.1 Single Measurements: Digital Raw and SSC Results

The ZSSC3230 generates digital raw values, which are processed by the IC-internal math-core generating the SSCcorrected (linearized, temperature-compensated) output signal; see section 6.5.2 for details about SSC math, etc. In addition to the SSC-corrected digital measurement results, the ZSSC3230 can provide raw values with or without SSC correction for evaluation and/or calibration purposes. The respective results are provided at the digital interface as a 24-bit-wide data word. Raw values are LSB-aligned. SSC results are MSB-aligned.

Bit-Number:	23	22	21	20	 2	1	0
Meaning, Weighting:	-20	2-1	2-2	2-3	 2 <sup>-21</sup>	2-22	2-23

#### Table 13. Data Format of Raw ADC Readings

#### Table 14. Data Format of Corrected SSC Results

Bit-Number:	23	22	21	20	 2	1	0
Meaning, Weighting:	2 <sup>0</sup>	2-1	2-2	2 <sup>-3</sup>	 2 <sup>-21</sup>	2-22	2 <sup>-23</sup>

The ZSSC3230 can process and digitize the following signals:

- Direct sensor signal inputs; i.e. perform sensor measurements, SM
- Auto-zero signals for the sensor channel, referred to as AZS
- Direct temperature signal inputs; i.e. perform temperature measurements, TM
- Auto-zero signals for the temperature channel, referred to as AZT

The utilization of auto-zero measurements allows inherent compensation for long-term drift effects of the ZSSC3230, such that the risk of lifetime signal degradation for the application and smart sensor is minimized. For the auto-zero measurement, the sensor signal remains the input for the auto-zero measurement with the gain and ADC setups the same as for the original signal measurement, but with swapped inputs and offset configurations of the PGA and ADC such that the following holds for the resulting raw value:

- Sensor raw value with auto-zero: S\_raw = 0.5 \* (SM AZS)
- Temperature raw value with auto-zero:  $T_raw = 0.5 * (TM AZT)$

Enabling auto-zero measurements is strongly recommended.

The NVM configuration and measurement request commands can be used to select which effective measurements are conducted, processed, and provided at the digital interface. The possible options for a single measurement request and output are the following:

- SSC-corrected sensor readings (requested by the "Measure" command AA<sub>HEX</sub>) generating an output of SSC-corrected, 24-bit sensor data followed by SSC-corrected, 24-bit temperature data.
- Raw sensor measurement with auto-zero correction (requested by the "Raw Sensor Measure" command A2<sub>HEX</sub>) generating an output of raw, 24-bit sensor data.
- Raw temperature measurement with auto-zero correction (requested by the "Raw Temperature Measure" command A6<sub>HEX</sub>) generating an output of raw, 24-bit temperature data.

### 6.7.2 Digital Commands

The availability of commands depends on the active Main Operating Mode: Command, Sleep, or Cyclic Measurement Mode.

Command Code (Byte)	Return	Description	Available in Sleep Mode	Available in Command Mode	Available in Cyclic Measurement Mode
$00_{HEX}$ to $1F_{HEX}$	16-bit data	Memory Read: Read address $00_{HEX}$ to $1F_{HEX}$ .	Yes	Yes	No
20 <sub>HEX</sub> to 3C <sub>HEX</sub> followed by data (0000 <sub>HEX</sub> to FFFF <sub>HEX</sub> )	_	<b>Memory Write:</b> Write data to addresses $00_{HEX}$ to $1C_{HEX}$ (the NVM-register address is the command minus $20_{HEX}$ ).	Yes	Yes	No
90 <sub>HEX</sub>	-	<b>Calculate NVM Checksum:</b> Calculate the checksum for the NVM and write it to the memory.	Yes	Yes	No
$A2_{HEX}$ followed by data $0000_{HEX}$	24-bit raw data	Raw Sensor Measurement:* Conduct a sensor measurement without SSC correction. The configuration is loaded to the controlling shadow registers from the <i>Sensor_config</i> register in NVM. Note: The auto-zero sensor measurement is also performed.	Yes	Yes	No
A3 <sub>HEX</sub> followed by data ssss <sub>HEX</sub>	24-bit raw data	Raw Sensor Measurement:* Conduct a sensor measurement without SSC correction. The ssss is the user's configuration setting for the measurement provided via the interface. The format and purpose of the configuration bits must be according to the definitions for <i>Sensor_config</i> . Note: The auto-zero sensor measurement is also performed.	Yes	Yes	No
$A6_{HEX}$ followed by data $0000_{HEX}$	24-bit raw data	<b>Raw Temperature Measurement:</b> * Conduct a temperature measurement without SSC correction. The configuration is loaded to the controlling shadow registers from the <i>extTemp_Config1/2</i> or <i>T_config1/2</i> registers in NVM as well as the <i>SSF1/2</i> registers. Note: Auto-zero-sensor measurement is performed.	Yes	Yes	No
A8 <sub>HEX</sub>	_	<b>START_SLEEP:</b> Exit Command Mode or Cyclic Measurement Mode and transition to Sleep Mode. Note: The response to Start_Sleep is only the status byte.	No	Yes	Yes
A9 <sub>HEX</sub>	_	<b>START_CM:</b> Enter Command Mode and enable/allow respective commands. This command must be sent as the first command after power-up.	No	Yes	No
AA <sub>HEX</sub>	24-bit SSC- corrected sensor data and 24-bit SSC-corrected temperature data	<b>Measure</b> – trigger a full measurement (auto-zero-sensor, sensor, auto-zero-temperature, temperature) and perform the SSC correction.	Yes	Yes	No
AB <sub>HEX</sub>	24-bit SSC-corrected sensor data and 24-bit SSC-corrected temperature data	measurement cycles, SSC corrections, and automatic,	Yes	Yes	No

#### Table 15. Command List

<sup>\*</sup> These commands can be used to conduct a measurement without SSC correction; e.g., during smart sensor calibration procedure. No digital correction is performed on the measurement result.

Command Code (Byte)	Return	Description	Available in Sleep Mode	Available in Command Mode	Available in Cyclic Measurement Mode
AC <sub>HEX</sub>		<b>Oversample-2 Measure:</b> * Complete multiple measurements for mean-value generation: 2 full measurements are performed (the same as measurements triggered with AA <sub>HEX</sub> , not cyclic) and the resulting mean value is provided as output.	Yes	Yes	No
AD <sub>HEX</sub>	24-bit SSC- corrected sensor data and	<b>Oversample-4 Measure:</b> * Complete multiple measurements for mean-value generation: 4 full measurements are performed (the same as AA <sub>HEX</sub> measurements, not cyclic) and the resulting mean value is provided as output.	Yes	Yes	No
AE <sub>HEX</sub>	24-bit SSC- corrected temperature data	<b>Oversample-8 Measure:</b> * Complete multiple measurements for mean-value generation: 8 full measurements are performed (the same as AA <sub>HEX</sub> measurements, not cyclic) and the resulting mean value is provided as output.	Yes	Yes	No
AF <sub>HEX</sub>		<b>Oversample-16 Measure:</b> * Complete multiple measurements for mean-value generation: 16 full measurements are performed (the same as AA <sub>HEX</sub> measurements, not cyclic) and the resulting mean value is provided as output.	Yes	Yes	No
B0 <sub>HEX</sub>	16-bit data output 0 pass / 1 fail	Broken Chip: Test resistance of corner wire.	Yes	Yes	No
B4 <sub>HEX</sub>	-	<b>Stop PDM:</b> This command can be used to stop the PDM in order to change the PDM enable in NVM. This command does not sent an ack.	No	No	Yes
$FX_{HEXX}$ followed by data $XX_{HEX}$	-	<b>Soft-Reset:</b> Full reset of digital part. Note: Any $FX_{HEX}$ command extended by one arbitrary data byte results in the soft reset. This command will not be answered by an acknowledge	Yes	Yes	Yes

### 6.7.3 Nonvolatile Memory (NVM)

In the ZSSC3230, the memory is organized in 16-bit wide registers and can be programmed multiple times (approximately 10000). There are 28 x 16-bit registers available for customer use. Each register can be re-programmed. Basically, there are two NVM content sectors:

- Customer Use Accessible by means of regular WRITE operations: 20<sub>HEX</sub> to 3C<sub>HEX</sub>. It contains the customer ID, interface setup data, measurement setup information, calibration coefficients, etc.
- Renesas Use Only accessible for WRITE operations by Renesas. This sector contains specific trim information and
  is programmed during manufacturing test by Renesas; e.g., configurations for the internal temperature sensor are
  stored there.



<sup>\*</sup> Use oversample measurements to obtain noise-minimized measurement results in Sleep or Command Mode. With higher oversampling factors, the command execution time increases proportionally.

### 6.7.4 Memory Contents

NVM Address	Word/Bi t Range	Default Setting	Word/Bit Field Name	Description
00 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Cust_ID0	Customer ID byte 0 (combines with memory word $01_{\text{HEX}}$ to form the customer ID).*
01 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Cust_ID1	Customer ID byte 1 (combines with memory word $00_{\text{HEX}}$ to form the customer ID).
Interface (	Configuratio	n		
		000 0000 <sub>BI</sub>		I2C and OWI slave address; valid range: 00 <sub>HEX</sub> to 7F <sub>HEX</sub> (default: 48 <sub>HEX</sub> ).
	6:0	N	Slave_Addr	Note: Address codes $04_{\text{HEX}}$ to $07_{\text{HEX}}$ are reserved for entering the I2C High Speed Mode.
				Interrupt configuration, EOC pin functionality:
				00 End-of-conversion signal
				01 0-1 transition if threshold1 (TRSH1) is exceeded and 1-0 transition if threshold1 is underrun again
			INT_setup	10 0-1 transition if threshold1 is underrun and 1-0 transition if threshold1 is exceeded again
	8:7	00 <sub>BIN</sub>		11 EOC is determined by threshold settings (see section 6.6.3):
				If (TRSH1 > TRSH2) then EOC/INT (interrupt level) = 0 if (TRSH1 > MEAS $\geq$ TRSH2) where MEAS is the conditioned measurement result.
				Otherwise EOC/INT=1.
			If (TRSH1 $\leq$ TRSH2) then EOC = 1 if (TRSH1 $\leq$ MEAS $<$ TRSH2).	
				Otherwise EOC = 0.
				Enables PDM-output:
$02_{\text{HEX}}$	9	0 <sub>BIN</sub>	PDM_enable	$0 \Leftrightarrow PDM \text{ output disabled} \qquad 1 \Leftrightarrow PDM \text{ output enabled}$
				If PDM_enable bit is 1, the ZSSC3230 will start after reset without any further command in Cyclic Measurement Mode
	10	0 <sub>BIN</sub>	Reserved	
	11	0	sigipy	Enables input signal inversion ("1-1/C") in conditioning math:
		0 <sub>BIN</sub>	siginv	$0 \Leftrightarrow "1-1/C" \text{ disabled} \qquad 1 \Leftrightarrow "1-1/C" \text{ enabled}$
				Update period (ZSSC3230 sleep time, except oscillator) in cyclic operation:
				000 ⇔ 0.0ms (= PDM default) 100 ⇔ 1333ms
				001 ⇔ 167ms 101 ⇔ 2667ms
	14:12 000 <sub>BIN</sub>	000 <sub>BIN</sub>	CYC_period	010 ⇔ 333ms 110 ⇔ 5333ms
				011 ⇔ 666ms 111 ⇔ Not assigned
	15	0	SOT output	Type/shape of second-order curve correction for the sensor signal.
	15	O <sub>BIN</sub>	SOT_curve	$0 \Leftrightarrow$ parabolic curve $1 \Leftrightarrow$ s-shaped curve

Table 16. Memory (NVM) Content Assignments

<sup>\*</sup> For  $I^{3}C$  operation, this should contain the Legacy Virtual Register "LVR" info: 0x1X ... Index 0; Fast Mode supported.

NVM Address	Word/Bi t Range	Default Setting	Word/Bit Field Name	Description	
Signal Co	nditioning Pa	arameters			
03 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Offset_S[15:0]	Bits [15:0] of the 24-bit-wide sensor offset correction coefficient Offset_S. (MSBs of this coefficient including sign are $Offset_S$ [23:16], which are bits [15: in $0D_{\text{HEX}}$ .)	
04 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Gain_S[15:0]	Bits [15:0] of the 24-bit-wide value of the sensor gain coefficient <i>Gain_S</i> . (MSBs of this coefficient including sign are <i>Gain_S</i> [23:16], which are bits [7:0] in $0D_{\text{HEX}}$ .)	
05 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Tcg[15:0]	Bits [15:0] of the 24-bit-wide coefficient <i>Tcg</i> for the temperature correction of the sensor gain. (The MSBs of this coefficient including sign are <i>Tcg</i> [23:16], which are bits [15:8] in $0E_{HEX}$ .)	
06 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Tco[15:0]	Bits [15:0] of the 24-bit-wide coefficient <i>Tco</i> for temperature correction of the sensor offset. (The MSBs of this coefficient including sign are <i>Tco</i> [23:16], which are bits [7:0] in $0E_{HEX}$ .)	
07 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	SOT_tco[15:0]	Bits [15:0] of the 24-bit-wide $2^{nd}$ order term $SOT\_tco$ applied to Tco. (The MSBs of this term including sign are $SOT\_tco$ [23:16], which are bits[15:8] in $0F_{HEX}$ .)	
08 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	SOT_tcg[15:0]	Bits [15:0] of the 24-bit-wide $2^{nd}$ order term $SOT\_tcg$ applied to Tcg. (The MSBs of this term including sign are $SOT\_tcg$ [23:16], which are bits[7:0] in $0F_{HEX}$ .)	
09 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	SOT_sens[15:0]	Bits [15:0] of the 24-bit-wide $2^{nd}$ order term <i>SOT_sens</i> applied to the sensor readout. (The MSBs of this term including sign are <i>SOT_sens</i> [23:16], which are bits[15:8] in $10_{HEX}$ .)	
0A <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Offset_T[15:0]	Bits [15:0] of the 24-bit-wide temperature offset correction coefficient <i>Offset_T</i> . (MSBs of this coefficient including sign are <i>Offset_T</i> [23:16]; i.e., bits[7:0] in $10_{\text{HEX}}$ .)	
0B <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Gain_T[15:0]	Bits [15:0] of the 24-bit-wide absolute value of the temperature gain coefficient <i>Gain_T</i> . (The MSBs of this coefficient including sign are <i>Gain_T</i> [23:16], which are bits[15:8] in $11_{HEX}$ .)	
0C <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	SOT_T[15:0]	Bits [15:0] of the 24-bit-wide $2^{nd}$ -order term $SOT_T$ applied to the temperature reading. (The MSBs of this coefficient including sign are $SOT_T$ [23:16], which are bit[7:0] in 11 <sub>HEX</sub> .)	
	7:0	00 <sub>HEX</sub>	Gain_S[23:16]	Bits [23:16] including sign for the 24-bit-wide sensor gain correction coefficient Gain_S. (The LSBs of this coefficient are Gain_S[15:0] in register $03_{HEX}$ .)	
		Offset_S[23:16]	Bits [23:16] including sign for the 24-bit-wide sensor offset correction coefficient <i>Offset_S</i> . (The LSBs are <i>Offset_S</i> [15:0] in register 04 <sub>HEX</sub> .)		
	7:0	00 <sub>HEX</sub>	Tco[23:16]	Bits [23:16] including sign for the 24-bit-wide coefficient <i>Tco</i> for temperature correction for the sensor offset. (The LSBs are <i>Tco</i> [15:0] in register $05_{HEX}$ .)	
0E <sub>HEX</sub>	15:8	00 <sub>HEX</sub>	Tcg[23:16]	Bits [23:16] including sign for the 24-bit-wide coefficient <i>Tcg</i> for the temperature correction of the sensor gain. (The LSBs are <i>Tcg</i> [15:0] in register $06_{\text{HEX}}$ .)	
	7:0	00 <sub>HEX</sub>	SOT_tcg[23:16]	Bits [23:16] including sign for the 24-bit-wide $2^{nd}$ order term $SOT\_tcg$ applied to Tcg. (The LSBs are $SOT\_tcg$ [15:0] in register $07_{HEX}$ .)	
		Bits [23:16] including sign for the 24-bit-wide $2^{nd}$ order term $SOT_tco$ applied to Tco. (The LSBs are $SOT_tco$ [15:0] in register $08_{HEX}$ .)			
10	7:0	00 <sub>HEX</sub>	Offset_T[23:16]	Bits [23:16] including sign for the 24-bit-wide temperature offset correction coefficient <i>Offset_T</i> . (The LSBs are <i>Offset_T</i> [15:0] in register 09 <sub>HEX</sub> .)	
		Bits [23:16] including sign for the 24-bit-wide 2 <sup>nd</sup> order term <i>SOT_sens</i> applied to the sensor readout. (The LSBs are <i>SOT_sens</i> [15:0] in register 0A <sub>HEX</sub> .)			
11 <sub>HEX</sub>	7:0	00 <sub>HEX</sub>	SOT_T[23:16]	Bits [23:16] including sign for the 24-bit-wide $2^{nd}$ -order term $SOT_T$ applied to the temperature reading. (The LSBs are $SOT_T$ [15:0] in register $0B_{HEX}$ .)	



NVM Address	Word/Bi t Range	Default Setting	Word/Bit Field Name		Description	
	15:8	00 <sub>HEX</sub>	Gain_T[23:16]	Bits [23:16] including sign for the 24-bit-wide absolute value of the temperatu gain coefficient <i>Gain_T</i> . (The LSBs are <i>Gain_T</i> [15:0] in register $0C_{\text{HEX}}$ .)		
Measurem	nent Configu	ration (Senso	r_config) Register			
			shift_cap	Defines the zero shift capacitance ⇔ input offset shift to cancel the static input capacitance of the sensor:		
				00 0000 ⇔ no offset shift	00 0111 ⇔1.75pF	
				00 0001 ⇔ 0.25pF	00 1000 ⇔2.00pF	
				00 0010 ⇔0.50pF	00 1001 ⇔2.25pF	
	5:0	00 0000 <sub>BIN</sub>		00 0011 ⇔0.75pF		
				00 0100 ⇔1.00pF	11 1101 ⇔15.00pF	
				00 0101 ⇔1.25pF	11 1110 ⇔15.50pF	
				00 0110 ⇔1.50pF	11 1111 ⇔15.75pF	
				Note: the offset shift capacitance r capacitance's range (see cap_ran	nust not exceed the selected input ge).	
				Defines the absolute number of bits for the A2D conversion:		
	7:6	00 <sub>BIN</sub>	adc_bits	00 ⇔12-bit	10 ⇔16-bit	
				01 ⇔14-bit (default)	11 ⇔18-bit	
	8	0 <sub>BIN</sub>	noise_mode	Select between control sequences for noise-quality vs. energy consumption optimization:		
10	C C	OBIN		0 ⇔ Low Current Mode	1 ⇔ Low Noise Mode	
12 <sub>HEX</sub>		0 0000 <sub>bin</sub>	cap_range	Selection maximum possible external signal capacitance; i.e. the capacitance sensor range (without any offset):		
	13:9			00000 ⇔ 0.5pF	10000 ⇔ 8.5pF	
				00001 ⇔ 1.0pF	10001 ⇔ 9.0pF	
				00010 ⇔ 1.5pF	10010 ⇔ 9.5pF	
				00011 ⇔ 2.0pF	10011 ⇔ 10.0pF	
				00100 ⇔ 2.5pF	10100 ⇔ 10.5pF	
				00101 ⇔ 3.0pF	10101 ⇔ 11.0pF	
				00110 ⇔ 3.5pF	10110 ⇔ 11.5pF	
				00111 ⇔ 4.0pF	10111 ⇔ 12.0pF	
				01000 ⇔ 4.5pF	11000 ⇔ 12.5pF	
				01001 ⇔ 5.0pF	11001 ⇔ 13.0pF	
				01010 ⇔ 5.5pF	11010 ⇔ 13.5pF	
				01011 ⇔ 6.0pF	11011 ⇔ 14.0pF	
				01100 ⇔ 6.5pF	11100 ⇔ 14.5pF	
				01101 ⇔ 7.0pF	11101 ⇔ 15.0pF	
				01110 ⇔ 7.5pF	11110 ⇔ 15.5pF	
				01111 ⇔ 8.0pF	11111 ⇔ 16.0pF	

NVM Address	Word/Bi t Range	Default Setting	Word/Bit Field Name	Description	
	14	O <sub>BIN</sub>	sensor_leakage	Option to enable sensor element's leakage current compensation (due to sensor element's parasitic resistance) ⇔ leakage cancellation leads to loss of dynamic range and decrease of SNR (loss of 1 bit of effective resolution).	
				The following setups are possible:	
12 <sub>HEX</sub>	14			0 ⇔ no sensor leakage cancellation; full internal dynamic range; full Vref applied to external sensor	
(Continued )				1 ⇔ sensor leakage cancellation enabled; applied voltage at external sensor of 0.5 * Vref (loss of 1 bit of effective resolution)	
				Selection of applied (external) sensor capacitance:	
			sensecap_type	$0 \Leftrightarrow$ "differential" sensor capacitance between C0 and CC (CC') pads	
	15	O <sub>BIN</sub>		1 ⇔ single ended sensor capacitance between VSS and CC (CC') pad; applied voltage at external sensor of 0.5 × Vref (loss of 1 bit of effective resolution)	
Interrupt L	evel Setup a	and Post-Cali	bration (Digital) Offs	et Calibration	
13 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	TRSH1[15:0]Bits [15:0] of the 24-bit-wide interrupt threshold1, TRSH1. (The MSBs f threshold are TRSH1[23:16], which are bits [7:0] of register 15 HEX.)		
14 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	TRSH2[15:0]	Bits [15:0] of the 24-bit-wide interrupt threshold2, <i>TRSH2</i> . (The MSBs for this threshold are <i>TRSH2</i> [23:16], which are bits[15:8] of register $15_{HEX}$ .)	
15	7:0			Bits [23:16] of the 24-bit-wide interrupt threshold1, <i>TRSH1</i> . (The LSBs for this threshold are <i>TRSH1</i> [15:0], which are bits[15:0] of register $13_{HEX}$ .)	
IOHEX	15 <sub>HEX</sub> 15:8 00 <sub>HEX</sub>		TRSH2[23:16]	Bits [23:16] of the 24-bit-wide interrupt threshold2, <i>TRSH2</i> . (The LSBs for this threshold are <i>TRSH2</i> [15:0], which are bits[15:0] of register $14_{HEX}$ .)	
16 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	SENS_Shift[15:0]Bits [15:0] of the post-calibration sensor offset shift coefficient SENS_Shift. (The MSBs of SENS_Shift are bits [7:0] of register 18 <sub>HEX</sub> .)		
17 <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	T_Shift[15:0]	Bits [15:0] of the post-calibration temperature offset shift coefficient <i>T_Shift</i> . (The MSBs of <i>T_Shift</i> are bits [15:8] of register $18_{HEX}$ .)	
18	7:0	00 <sub>HEX</sub>	SENS_Shift[23:16 ]	Bits [23:16] of the post-calibration sensor offset shift coefficient SENS_Shift. (The LSBs of SENS_Shift are in register $16_{HEX}$ .)	
18 <sub>HEX</sub>	15:8	00 <sub>HEX</sub>	T_Shift[23:16]	Bits [23:16] of the post-calibration temperature offset shift coefficient $T_Shift$ . (The LSBs of $T_Shift$ are in register $17_{HEX}$ .)	



#### ZSSC3230 Datasheet

NVM Address	Word/Bi t Range	Default Setting	Word/Bit Field Name	Description	
Configura	tion Registe	r			
	1:0	00 <sub>BIN</sub>	CC_pin_selection	Defines which pin is used for measurement (CC and/or CC'): 00 ⇔ no input 01 ⇔ CC 10 ⇔ CC' 11 ⇔ CC and CC'	
	2	0 <sub>BIN</sub>	Dither	Enable/disable digital dithering to improve EMI performance:         0 ⇔ No dithering       1 ⇔ Dithering enabled	
19 <sub>HEX</sub>	3	O <sub>BIN</sub>	En_sh2	Enable Subtraction Mode in grounded mode (see section 6.2.5):         0 ⇔ Disabled       1 ⇔ Enabled	
	4	0 <sub>BIN</sub>	En_shlddrv	Enable active shield drive at the C0 pin (see section 6.2.4):         0 ⇔ Disabled       1 ⇔ Enabled	
	5	O <sub>BIN</sub>	Dyn_imp	Enables higher drive current in analog front end, which will be needed if the sensor range is much smaller than the shift capacitor:         0 ⇔ Disabled       1 ⇔ Enabled	
	6	O <sub>BIN</sub>	Test_cap	Enables an internal reference sensor capacitor of approx. 2pF in parallel to sensor input: 0 ⇔ Disabled 1 ⇔ Enabled	
	15:7		Reserved	Renesas lot tracking information; can be overwritten and used as free space for customer use.	
1A <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Reserved	Renesas lot tracking information; can be overwritten and used as free space for customer use.	
1B <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	Reserved	Renesas lot tracking information; can be overwritten and used as free space for customer use.	
1C <sub>HEX</sub>	15:0	0000 <sub>HEX</sub>	CRC	Generated checksum (CRC) for whole memory through a linear feedback shift register (LFSR); Signature is checked upon power-up to ensure memory content integrity	

The NVM-consistency checksum is calculated (IC-internally for the whole NVM) using the polynomial:  $x^{16} + x^{15} + x^2 + 1$ . The checksum verification is only realized directly after V<sub>DD</sub> power-on. If the checksum is successfully verified, then the "Memory Error" status bit is set to 0<sub>BIN</sub>.



## 7. Package Outline Drawings

The package outline drawing VFQFPN package is appended at the end of this document and are accessible from the link below. The package information is the most current data available.

Package Outline Drawing PSC-4192-01 NLG24P1 24-VFQFPN 4.0 x 4.0 x 0.9 mm Body, 0.5mm Pitch

## 8. Marking Diagram

3230B YYWW XXXXX

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- 1. Line 1 is the truncated part number.
- 2. Line 2 "YYWW" are the last two digit of the year and week that the part was assembled.
- 3. Line 3 "XXXXX" denotes assembly lot number.

## 9. Ordering Information

Orderable Part Number	Description and Package	MSL Rating	Carrier Type	Temperature
ZSSC3230BC1B	Dice on 304µm wafer no inking	Not applicable	Wafer Box	-40 to 85°C
ZSSC3230BC2B	Dice on 725µm wafer no inking	Not applicable	Wafer Box	-40 to 85°C
ZSSC3230BI1B	Dice on 304µm wafer no inking	Not applicable	Wafer Box	-40 to 125°C
ZSSC3230BI2B	Dice on 725µm wafer no inking	Not applicable	Wafer Box	-40 to 125°C
ZSSC3230BC5B	Dice on 304µm wafer with inking	Not applicable	Wafer Box	-40 to 85°C
ZSSC3230BC6B	Dice on 725µm wafer with inking	Not applicable	Wafer Box	-40 to 85°C
ZSSC3230BI5B	Dice on 304µm wafer with inking	Not applicable	Wafer Box	-40 to 125°C
ZSSC3230BI6B	Dice on 725µm wafer with inking	Not applicable	Wafer Box	-40 to 125°C
ZSSC3230BC3R	$4 \times 4 \text{ mm}^2 \text{ PQFN}$	MSL1	13" Reel	-40 to 85°C
ZSSC3230BI3R	$4 \times 4 \text{ mm}^2 \text{ PQFN}$	MSL1	13" Reel	-40 to 125°C
ZSSC3230BI3W	$4 \times 4 \text{ mm}^2 \text{ PQFN}$	MSL1	7" Reel	-40 to 125°C
ZSSC3230KIT	ZSSC3230 Evaluation Board with USB Ca	ble and 5 Samples		

## 10. Glossary

Term	Description			
A2D	Analog-to-Digital			
ACK	Acknowledge (interface's protocol indicator for successful data/command transfer)			
ADC	Analog-to-Digital Converter or Conversion			
AGND	Analog Ground			
AZ	Auto-Zero (unspecific)			
AZS	Auto-Zero Measurement for (External) Sensor Path			
AZT	Auto-Zero Measurement for (External or Internal) Temperature Path			
CLK	Clock			
CVC	Charge-Voltage Converter			
DAC	Digital-to-Analog Converter or Conversion			
EOC	End of Conversion			
FSO	Full Scale Output (value in percent relative to the ADC maximum output code; resolution dependent)			
HVAC	Heating, Ventilation, and Air Conditioning			
LFSR	Linear Feedback Shift Register			
LSB	Least Significant Bit			
MSB	Most Significant Bit			
MSL	Moisture Sensitivity Level			
NACK	Not Acknowledge (interface's protocol indicator for unsuccessful data/command transfer)			
NVM	Nonvolatile Memory			
OpAmp	Operating Amplifier			
PGA	Programmable Gain Amplifier			
POR	Power-On Reset			
PSRR	Power Supply (Disturbance) Rejection Ratio			
ΡΤΑΤ	Proportional to Absolute Temperature			
S	SSC-Corrected Sensor Readout / Result			
SM	Sensor Measurement			
SNR	Signal to Noise Ratio			
SOT	Second-Order Term			
SSF	Smart-Sensor Function (specific NVM registers)			
Т	SSC-Corrected (additional) Temperature Readout / Result			
тс	Temperature Coefficient			

## **11. Revision History**

Revision Number	<b>Revision Date</b>	Description of Change	
1.4	Jun 10, 2025	<ul> <li>Default I2C-address correction to 48<sub>HEX</sub></li> <li>Wrong NVM lock information removed, there is no lock option in the ZSSC3230 NVM</li> <li>Correction of the EOC behavior description in section 6.6.3</li> </ul>	
1.3	Dec 1, 2022	Updated POD links in Package Outline Drawings.	
1.2	Oct 15, 2019	<ul> <li>Values updated for Power-up conditions</li> <li>Conditions updated for equations for the S-shaped SOT_curve setting</li> </ul>	
1.1	Sep 10, 2019	Initial release.	

